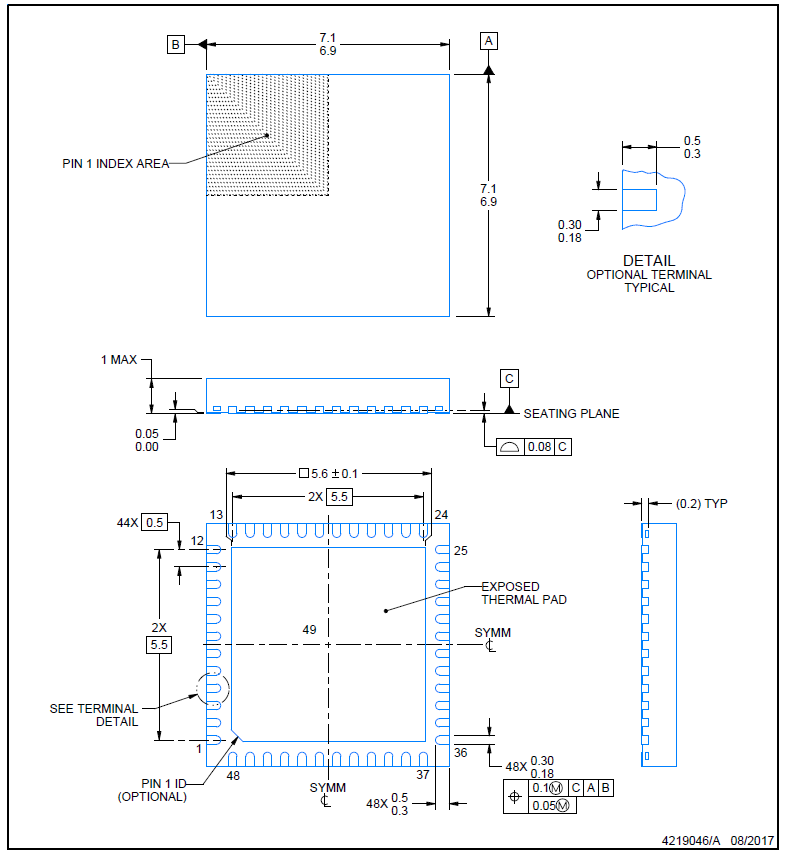
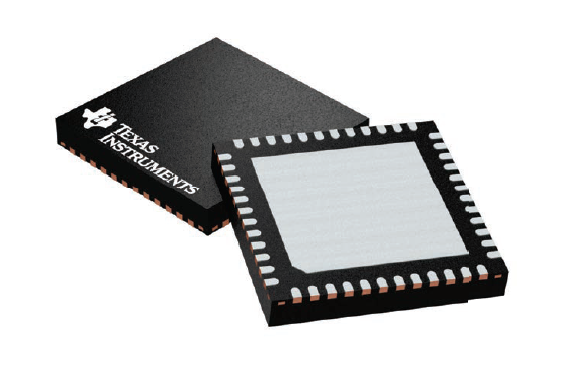
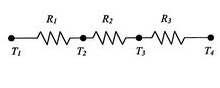
Annex 4.2

3. PMIC has an exposed thermal pad.



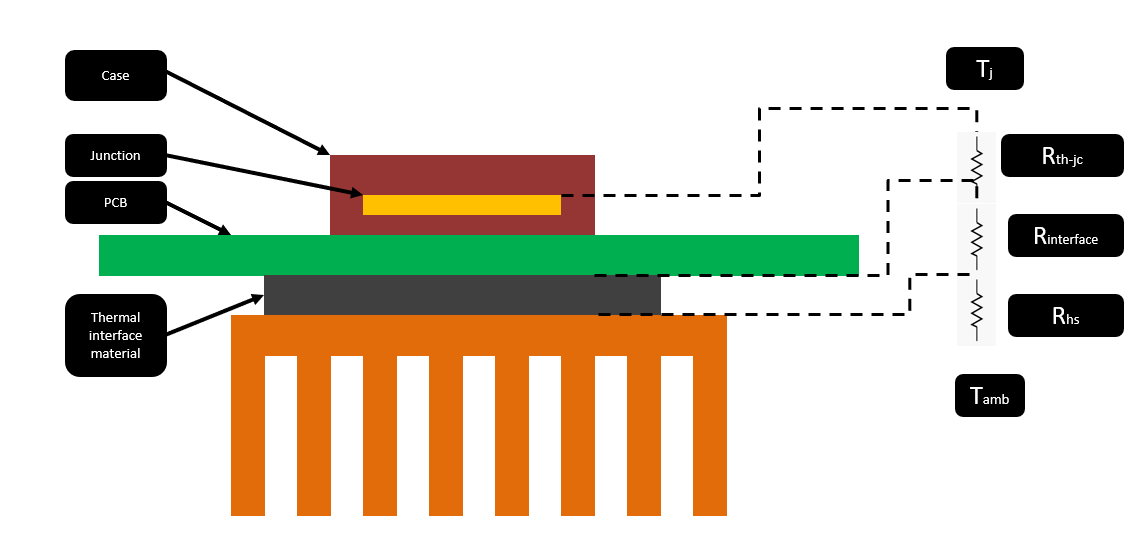
The conduction heat path from junction to heatsink is described in the image below:



Where T1= junction temperature; T2= case temperature; T3= PCB temperature (bottom side); T4= heatsink temperature (contact with TIM).

Between the PCB and heatsink there is a TIM (thermal interface material) – see Tflex-HR600.pdf. This TIM has its own thermal resistance.

TIM dimensions: 5x5x1.4mm



The general formula for thermal resistance for conduction mechanism is:

Where K is thermal conductivity, L [m] is the thermal path length, As is the cross-sectional area where the heat is applied.

Thermal resistance for one via (0.2mm diameter) is 241.6 degC/W